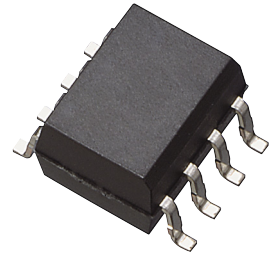


PC4D10SNIP0F Series

High Speed 10Mb/s, High CMR
Mini-flat 2-channel Package
*OPIC Photocoupler



■ Description

PC4D10SNIP0F Series contains a LED optically coupled to an OPIC.

It is packaged in a 8 pin mini-flat (2-ch output).

Input-output isolation voltage(rms) is 3.75 kV.

High speed response (TYP. 10Mb/s) and CMR is MIN. 10kV/μs.

■ Features

1. 2-ch output, 8 pin Mini-flat package
2. Double transfer mold package
(Ideal for Flow Soldering)
3. High noise immunity due to high instantaneous common mode rejection voltage (CM_H : MIN. 10kV/μs, CM_L : MIN. -10kV/μs)
4. High speed response
(t_{PHL} : TYP. 50ns, t_{PLH} : TYP. 48ns)
5. Isolation voltage between input and output ($V_{iso(rms)}$: 3.75kV)
6. Lead-free and RoHS directive compliant

■ Agency approvals/Compliance

1. Recognized by UL1577 (Double protection isolation), file No. E64380 (as model No. **PC4D10S**)
2. Approved by VDE, DIN EN60747-5-2^(*) (as an option), file No. 40009162 (as model No. **PC4D10S**)
3. Package resin : UL flammability grade (94V-0)

(*) DIN EN60747-5-2 : successor standard of DIN VDE0884.

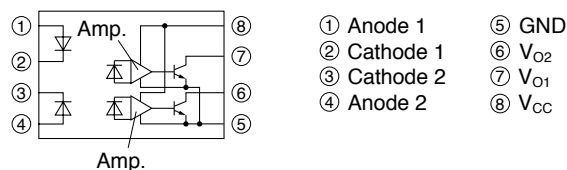
■ Applications

1. Programmable controller
2. Inverter

* "OPIC"(Optical IC) is a trademark of the SHARP Corporation. An OPIC consists of a light-detecting element and a signal-processing circuit integrated onto a single chip.

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Internal Connection Diagram

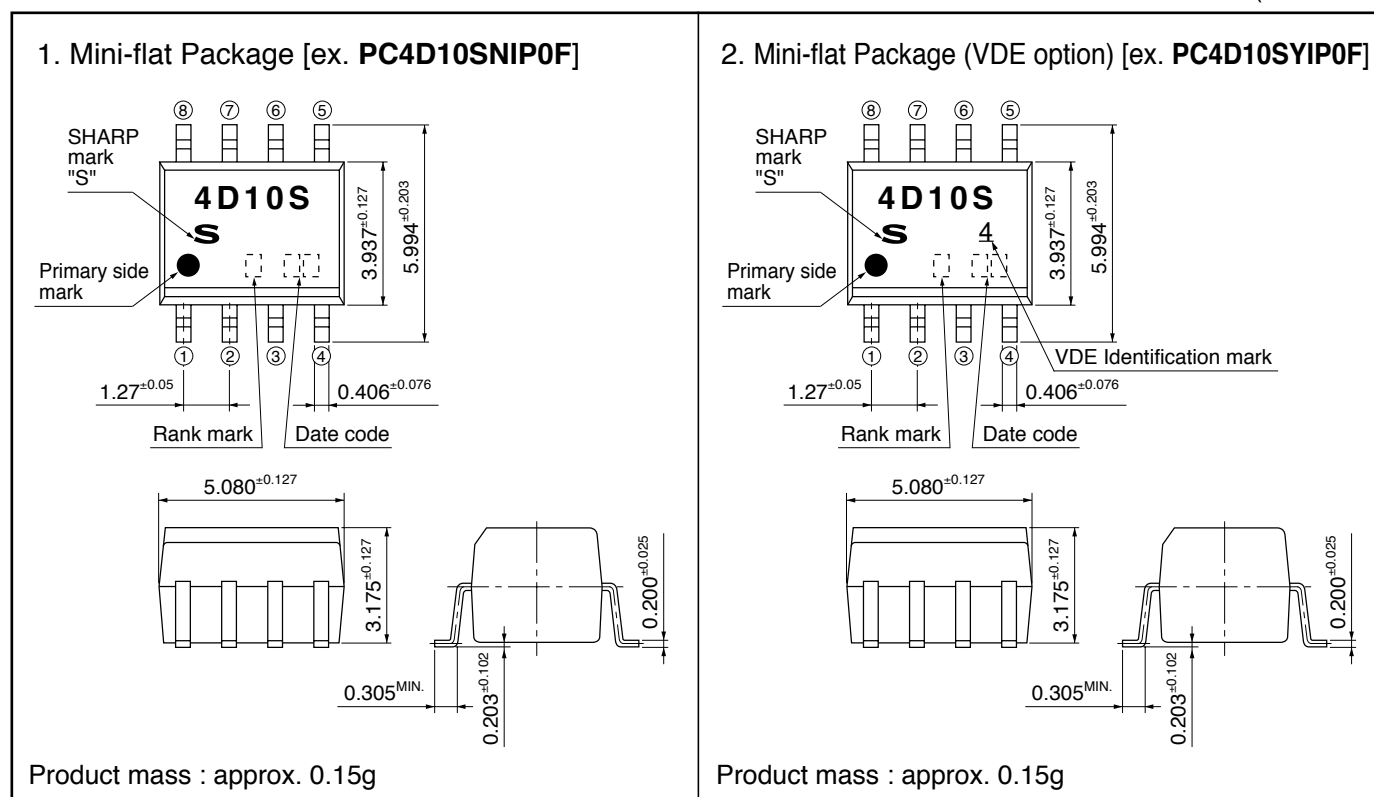


Truth table

Channel	Input	LED	Output
1	H	ON	L
	L	OFF	H
2	H	ON	L
	L	OFF	H

Outline Dimensions

(Unit : mm)



Plating material : Pd (Au flush)

Date code (2 digit)

1st digit				2nd digit	
Year of production				Month of production	
A.D.	Mark	A.D.	Mark	Month	Mark
1990	A	2002	P	January	1
1991	B	2003	R	February	2
1992	C	2004	S	March	3
1993	D	2005	T	April	4
1994	E	2006	U	May	5
1995	F	2007	V	June	6
1996	H	2008	W	July	7
1997	J	2009	X	August	8
1998	K	2010	A	September	9
1999	L	2011	B	October	O
2000	M	2012	C	November	N
2001	N	:	:	December	D

repeats in a 20 year cycle

Country of origin

Japan

Rank mark

With or without.

■ Absolute Maximum Ratings

(T_a=25°C)

Parameter		Symbol	Rating	Unit
Input	*1 Forward current	I _F	20	mA
	Reverse voltage	V _R	5	V
	Power dissipation	P _I	40	mW
Output	Supply voltage	V _{CC}	7	V
	Output collector voltage	V _O	7	V
	Output collector current	I _O	50	mA
	*1 Output collector power dissipation	P _C	60	mW
Operating temperature		T _{opr}	−40 to +85	°C
Storage temperature		T _{stg}	−55 to +125	°C
*2 Isolation voltage		V _{iso(rms)}	3.75	kV
*3 Soldering temperature		T _{sol}	270	°C

*1 No delating required up to 85°C

*2 40 to 60%RH, AC for 1minute, f=60Hz

*3 For 10s

■ Electro-optical Characteristics

(Unless otherwise specified T_a=−40 to 85°C)

Parameter		Symbol	Condition		MIN.	TYP.*4	MAX.	Unit	
Input	Forward voltage	V _F	T _a =25°C, I _F =10mA		1.4	1.5	1.75	V	
			I _F =10mA		1.3	–	1.8		
	Reverse current	I _R	T _a =25°C, V _R =5V		–	–	10	μA	
Terminal capacitance		C _t	Ta=25°C, V=0, f=1MHz		–	60	150	pF	
*5 Output	Low level output voltage	V _{OL}	I _{OL} =13mA, V _{CC} =5.5V, V _E =2V, I _F =5mA		–	0.4	0.6	V	
	High level output current	I _{OH}	V _{CC} =V _O =5.5V, I _F =250μA		–	0.02	100	μA	
	Low level supply current	I _{CCCL}	V _{CC} =5.5V, I _F =10mA		–	13	21	mA	
	High level supply current	I _{CCCH}	V _{CC} =5.5V, I _F =0		–	10	15	mA	
"High→Low" input threshold current		I _{FHL}	V _{CC} =5V, V _O =0.6V, R _L =350Ω		–	2.5	5	mA	
Isolation resistance		R _{ISO}	T _a =25°C, DC500V, 40 to 60%RH		5×10 ¹⁰	10 ¹¹	–	Ω	
Floating capacitance		C _f	T _a =25°C, V=0, f=1MHz		–	0.6	–	pF	
*5 Transfer characteristics	Response time	"High→Low" propagation delay time	t _{PHL}	V _{CC} =5V, I _F =7.5mA, R _L =350W, C _L =15pF	T _a =25°C	–	–	100	ns
						25	48	75	ns
		"Low→High" propagation delay time	t _{PLH}		T _a =25°C	–	–	100	ns
						25	50	75	ns
		*6 Distortion of pulse width	Δt _W		–	3.5	35	ns	
		Rise time	t _r		–	20	–	ns	
		Fall time	t _f		–	10	–	ns	
	Propagation delay skew	t _{PSK}	–	–	40	ns			
	Instantaneous common mode rejection voltage (High level output)		CM _H	I _F =0, V _{O(Min)} =2V,	T _a =25°C, V _{CC} =5V, V _{CM} =1kV _(P-P) , R _L =350Ω	10	20	–	kV/μs
	Instantaneous common mode rejection voltage (Low level output)		CM _L	I _F =7.5mA, V _{O(MAX)} =0.8V		–10	–20	–	kV/μs

*4 All typical values at V_{CC}=5V, T_a=25°C*5 It shall connect a by-pass capacitor of 0.01μF or more between V_{CC} (pin ⑧) and GND (pin ⑤) near the device, when it measures the transfer characteristics and the output side characteristics*6 Distortion of pulse width Δ_{tw}=|t_{PHL}–t_{PLH}|

Fig.1 Test Circuit for Propagation Delay Time and Rise Time, Fall Time

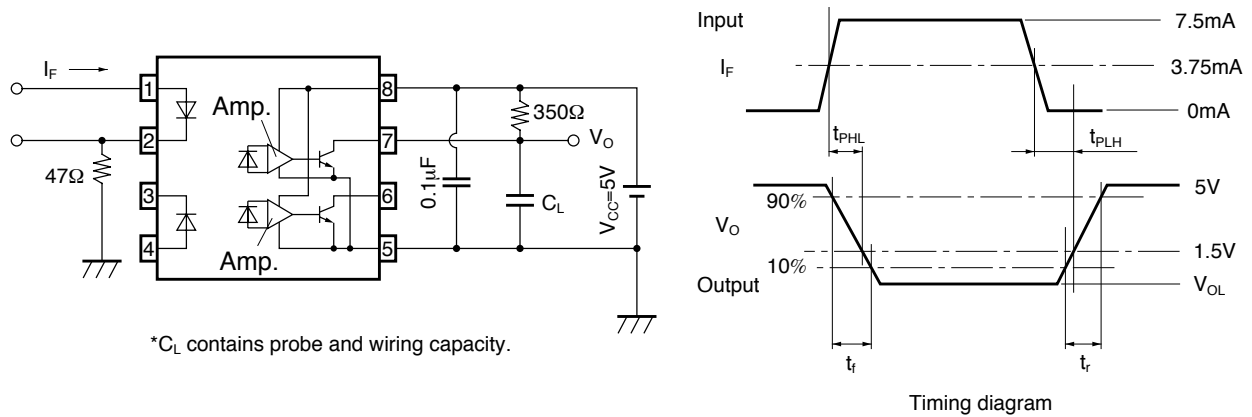


Fig.2 Test Circuit for Instantaneous Common Mode Rejection Voltage

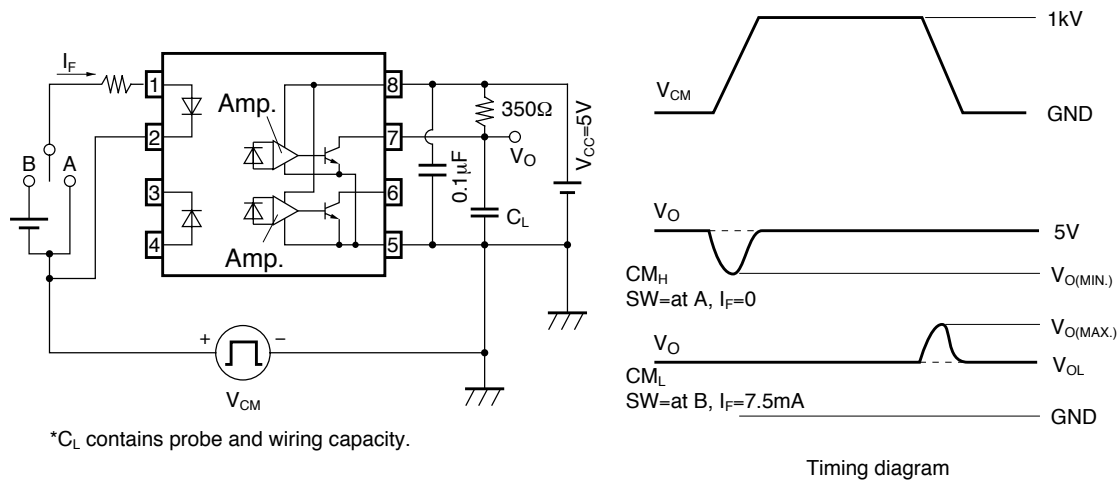


Fig.3 Forward Current vs. Ambient Temperature

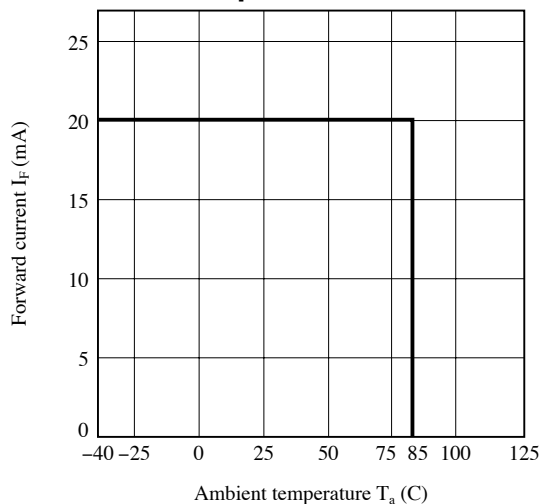


Fig.4 Output Collector Power Dissipation vs. Ambient Temperature

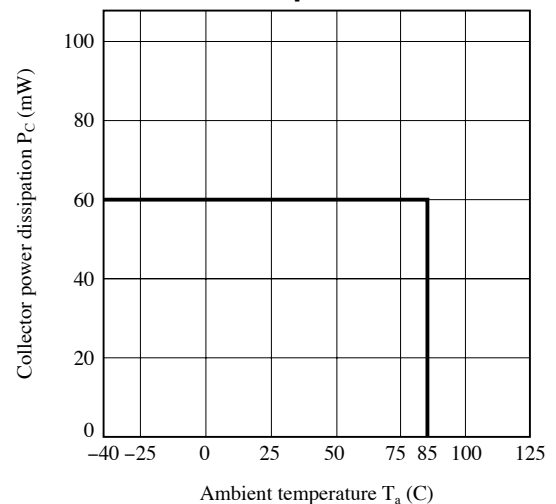


Fig.5 Forward Current vs. Forward Voltage

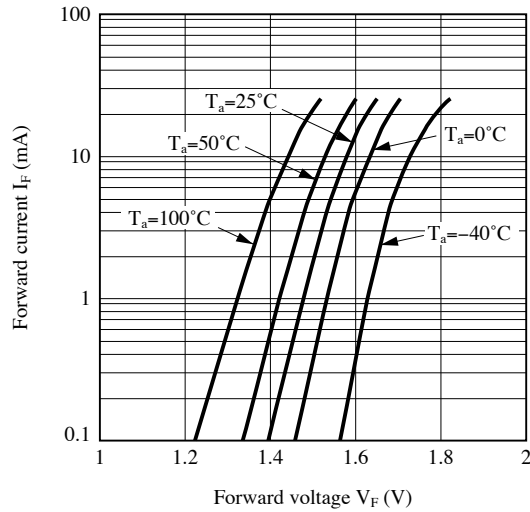


Fig.6 High Level Output Current vs. Ambient Temperature

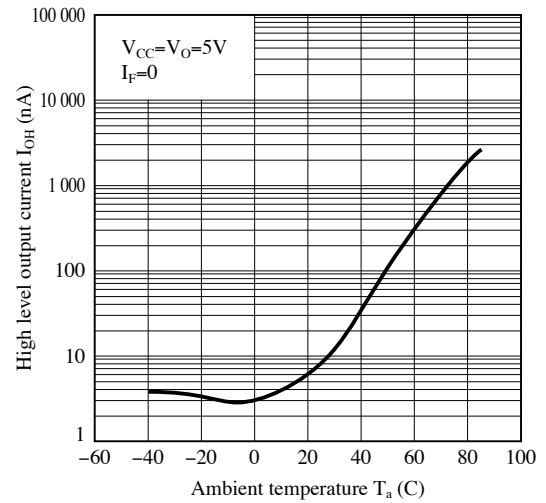


Fig.7 Low Level Output Voltage vs. Ambient Temperature

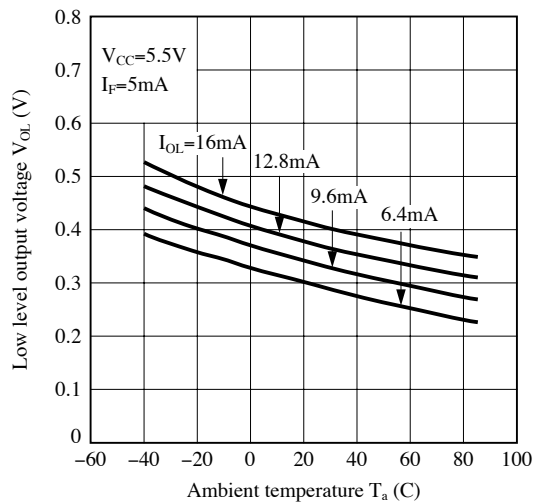


Fig.8 Output Voltage vs. Forward Current

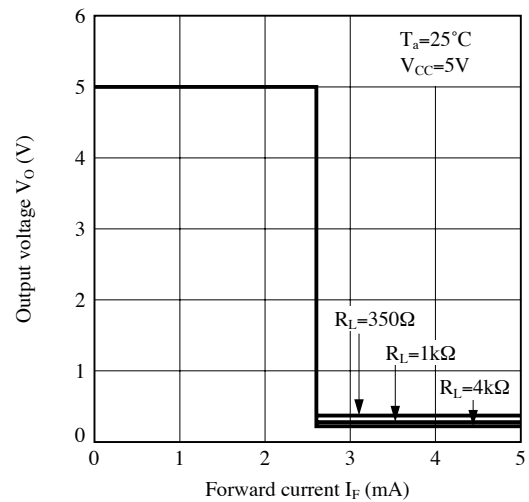


Fig.9 Input Threshold Current vs. Ambient Temperature

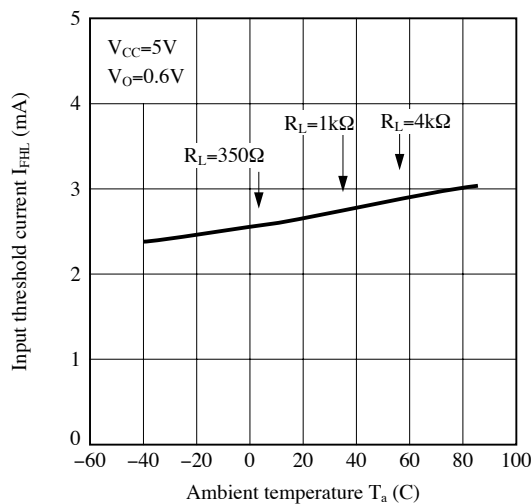


Fig.10 Propagation Delay Time vs. Forward Current

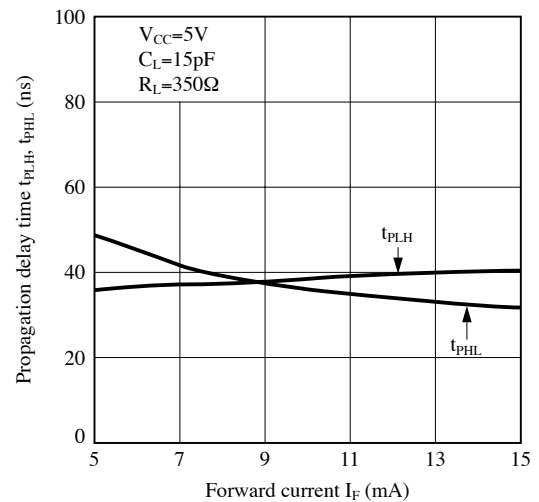


Fig.11-a Propagation Delay Time vs. Ambient Temperature

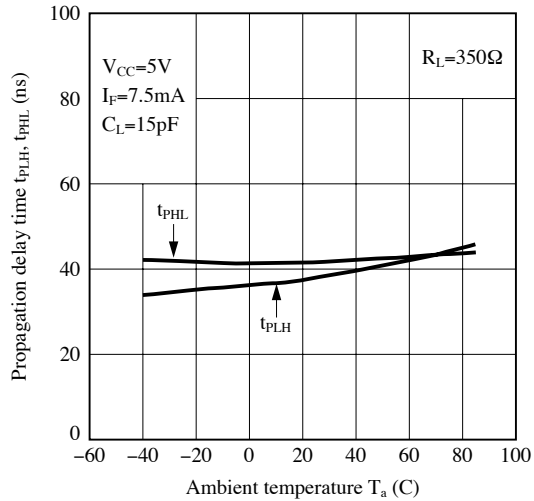


Fig.11-b Propagation Delay Time vs. Ambient Temperature

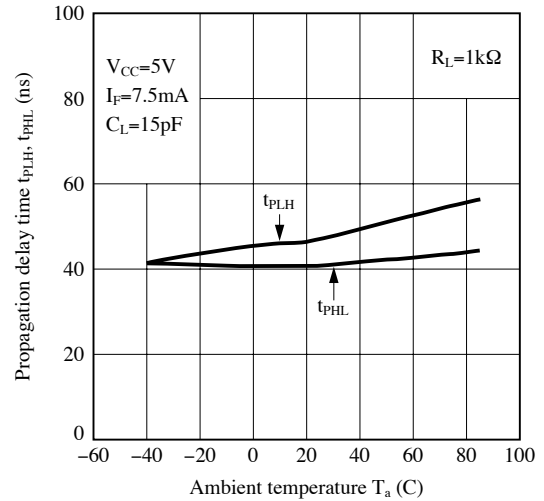


Fig.11-c Propagation Delay Time vs. Ambient Temperature

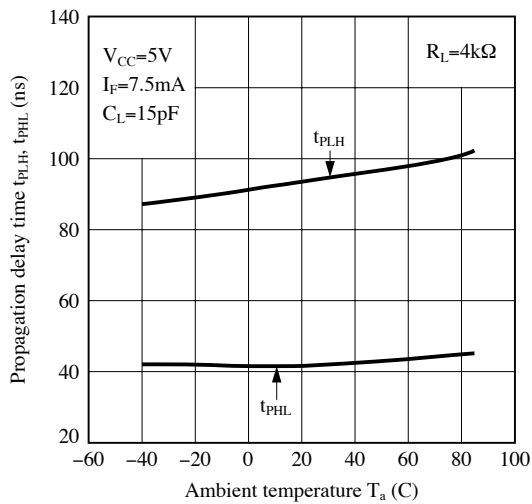


Fig.12 Pulse width Distortion vs. Ambient Temperature

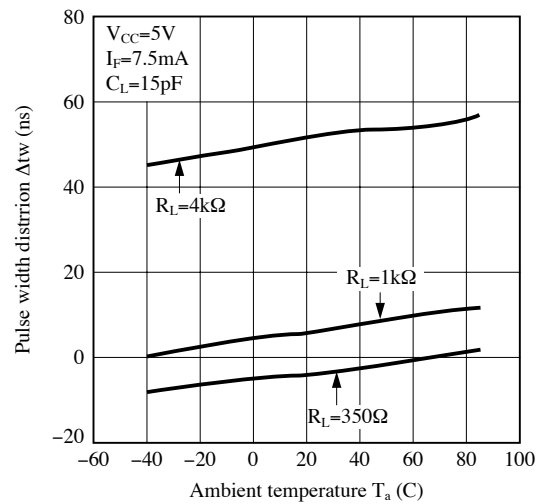
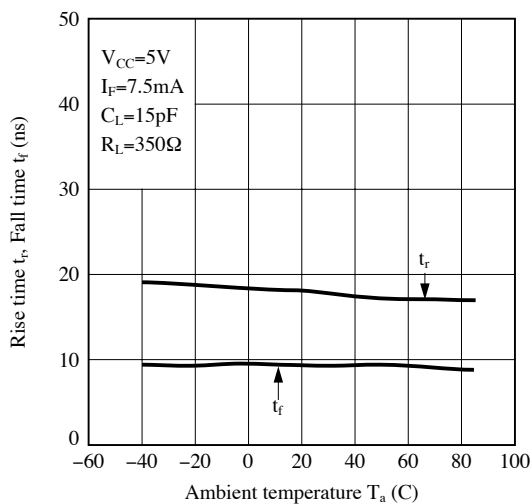


Fig.13 Rise Time / Fall Time vs. Ambient Temperature



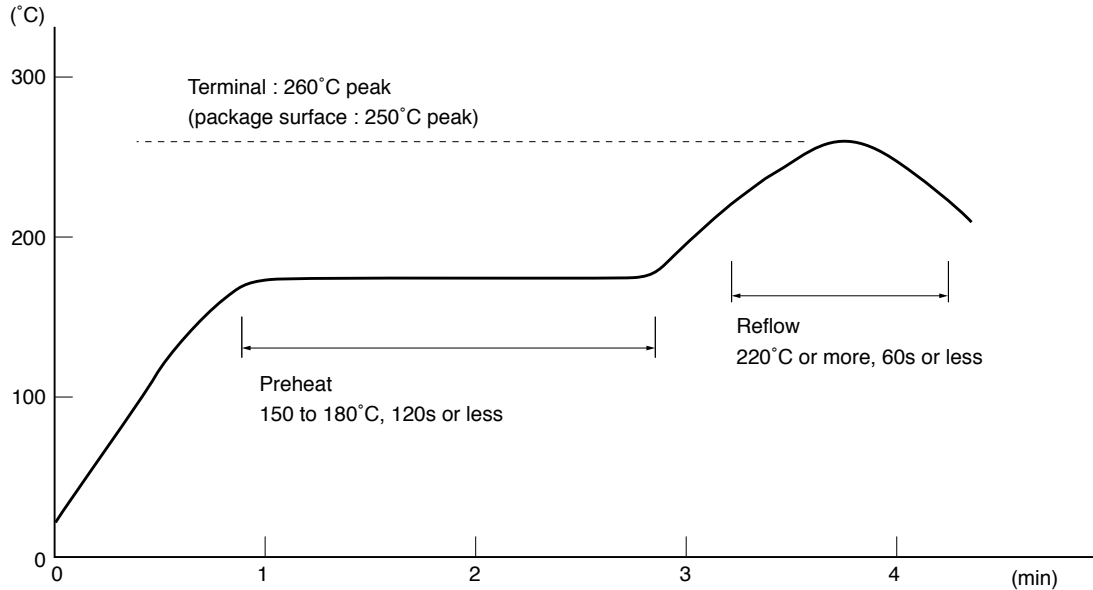
Remarks : Please be aware that all data in the graph are just for reference and anot for guarantee.

■ Manufacturing Guidelines

● Soldering Method

Reflow Soldering:

Reflow soldering should follow the temperature profile shown below.
Soldering should not exceed the curve of temperature profile and time.
Please don't solder more than twice.



Flow Soldering :

Due to SHARP's double transfer mold construction submersion in flow solder bath is allowed under the below listed guidelines.

Flow soldering should be completed below 270°C and within 10s.
Preheating is within the bounds of 100 to 150°C and 30 to 80s.
Please don't solder more than twice.

Hand soldering

Hand soldering should be completed within 3s when the point of solder iron is below 400°C.
Please don't solder more than twice.

Other notice

Please test the soldering method in actual condition and make sure the soldering works fine, since the impact on the junction between the device and PCB varies depending on the tooling and soldering conditions.

● Cleaning instructions**Solvent cleaning :**

Solvent temperature should be 45°C or below. Immersion time should be 3 minutes or less.

Ultrasonic cleaning :

The impact on the device varies depending on the size of the cleaning bath, ultrasonic output, cleaning time, size of PCB and mounting method of the device.

Therefore, please make sure the device withstands the ultrasonic cleaning in actual conditions in advance of mass production.

Recommended solvent materials :

Ethyl alcohol, Methyl alcohol and Isopropyl alcohol.

In case the other type of solvent materials are intended to be used, please make sure they work fine in actual using conditions since some materials may erode the packaging resin.

● Presence of ODC

This product shall not contain the following materials.

And they are not used in the production process for this product.

Regulation substances : CFCs, Halon, Carbon tetrachloride, 1.1.1-Trichloroethane (Methylchloroform)

Specific brominated flame retardants such as the PBB and PBDE are not used in this product at all.

This product shall not contain the following materials banned in the RoHS Directive (2002/95/EC).

- Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyls (PBB), Polybrominated diphenyl ethers (PBDE).

● Tape and Reel package

SMT Gullwing

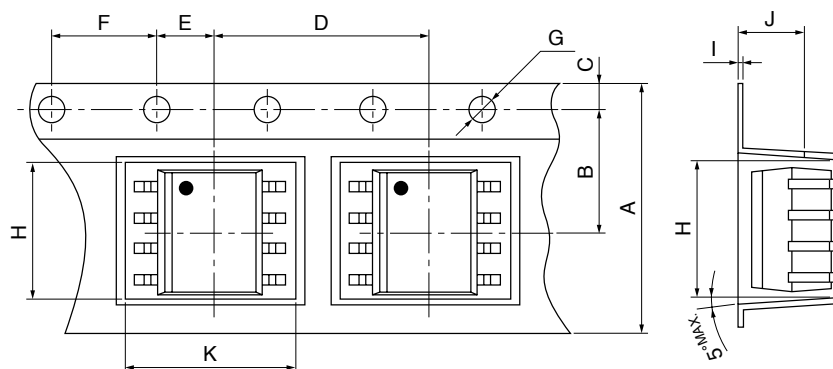
Package materials

Carrier tape : PS

Cover tape : PET (three layer system)

Reel : PS

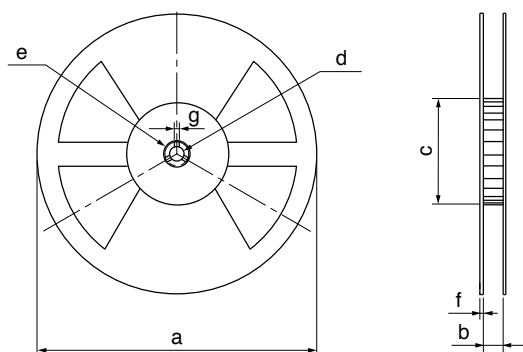
Carrier tape structure and Dimensions



Dimensions List (Unit : mm)

A	B	C	D	E	F	G
12.0 $\pm$ 0.3	5.50 $\pm$ 0.05	1.75 $\pm$ 0.10	8.0 $\pm$ 0.1	2.00 $\pm$ 0.05	4.0 $\pm$ 0.1	ϕ 1.55 $\pm$ 0.05
H	I	J	K			
5.4 $\pm$ 0.1	0.30 $\pm$ 0.05	3.7 $\pm$ 0.1	6.3 $\pm$ 0.1			

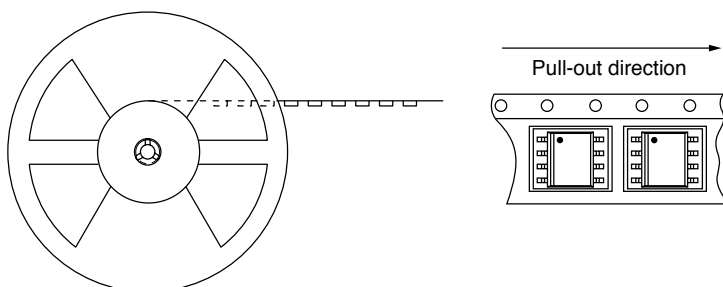
Reel structure and Dimensions



Dimensions List (Unit : mm)

a	b	c	d
ϕ 330	13.5 $\pm$ 1.5	ϕ 100 $\pm$ 1	ϕ 13.0 $\pm$ 0.2
e	f	g	
ϕ 21.0 $\pm$ 0.8	2.0TYP.	2.0 $\pm$ 0.5	

Direction of product insertion



[Packing : 1 500pcs/reel]

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(i) The devices in this publication are designed for use in general electronic equipment designs such as:

- Personal computers
- Office automation equipment
- Telecommunication equipment [terminal]
- Test and measurement equipment
- Industrial control
- Audio visual equipment
- Consumer electronics

(ii) Measures such as fail-safe function and redundant design should be taken to ensure reliability and safety when SHARP devices are used for or in connection

with equipment that requires higher reliability such as:

- Transportation control and safety equipment (i.e., aircraft, trains, automobiles, etc.)
- Traffic signals
- Gas leakage sensor breakers
- Alarm equipment
- Various safety devices, etc.

(iii) SHARP devices shall not be used for or in connection with equipment that requires an extremely high level of reliability and safety such as:

- Space applications
- Telecommunication equipment [trunk lines]
- Nuclear power control equipment
- Medical and other life support equipment (e.g., scuba).

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